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[ON Semiconductor](#)  
[NTUD3170NZT5G](#)

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# NTUD3170NZ

## Small Signal MOSFET

20 V, 220 mA, Dual N-Channel, 1.0 mm x 1.0 mm SOT-963 Package

### Features

- Dual N-Channel MOSFET
- Offers a Low  $R_{DS(ON)}$  Solution in the Ultra Small 1.0 x 1.0 mm Package
- 1.5 V Gate Voltage Rating
- Ultra Thin Profile (< 0.5 mm) Allows It to Fit Easily into Extremely Thin Environments such as Portable Electronics
- This is a Pb-Free Device

### Applications

- General Purpose Interfacing Switch
- Optimized for Power Management in Ultra Portable Equipment
- Analog Switch

### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	20	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	220
		$T_A = 85^\circ\text{C}$	160
		$t \leq 5 \text{ s}$	280
Power Dissipation (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	125
		$t \leq 5 \text{ s}$	200
Pulsed Drain Current	$t_p = 10 \mu\text{s}$	$I_{DM}$	800 mA
Operating Junction and Storage Temperature	$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$
Source Current (Body Diode) (Note 2)	$I_S$	200	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	$T_L$	260	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

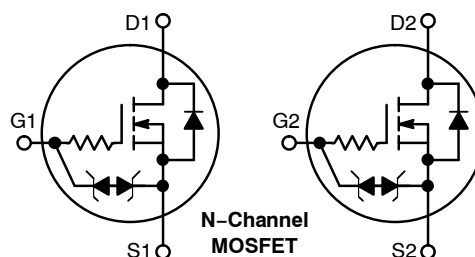
1. Surface-mounted on FR4 board using the minimum recommended pad size, 1 oz Cu.
2. Pulse Test: pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$



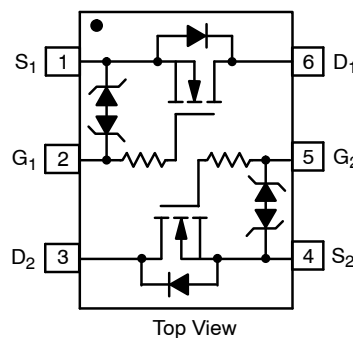
ON Semiconductor®

<http://onsemi.com>

$V_{(BR)DSS}$	$R_{DS(ON) \text{ MAX}}$	$I_D \text{ Max}$
20 V	1.5 $\Omega$ @ 4.5 V	0.22 A
	2.0 $\Omega$ @ 2.5 V	
	3.0 $\Omega$ @ 1.8 V	
	4.5 $\Omega$ @ 1.5 V	



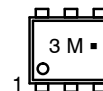
### PINOUT: SOT-963



### MARKING DIAGRAM



SOT-963  
CASE 527AD



- 3 = Specific Device Code
- M = Date Code
- = Pb-Free Package

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

## NTUD3170NZ

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 3)	$R_{\theta JA}$	1000	°C/W
Junction-to-Ambient – $t = 5$ s (Note 3)		600	

3. Surface-mounted on FR4 board using the minimum recommended pad size, 1 oz Cu.

### ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}, V_{DS} = 5\text{ V}$	$T_J = 25^\circ\text{C}$		50	nA
			$T_J = 85^\circ\text{C}$		200	nA
		$V_{GS} = 0\text{ V}, V_{DS} = 16\text{ V}$	$T_J = 25^\circ\text{C}$		100	nA
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 5.0\text{ V}$			$\pm 100$	nA

### ON CHARACTERISTICS (Note 4)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\ \mu\text{A}$	0.4		1.0	V
Drain-to-Source On Resistance	$R_{DS(ON)}$	$V_{GS} = 4.5\text{ V}, I_D = 100\text{ mA}$		0.75	1.5	$\Omega$
		$V_{GS} = 2.5\text{ V}, I_D = 50\text{ mA}$		1.0	2.0	
		$V_{GS} = 1.8\text{ V}, I_D = 20\text{ mA}$		1.4	3.0	
		$V_{GS} = 1.5\text{ V}, I_D = 10\text{ mA}$		1.8	4.5	
		$V_{GS} = 1.2\text{ V}, I_D = 1.0\text{ mA}$		2.8		
Forward Transconductance	$g_{FS}$	$V_{DS} = 5.0\text{ V}, I_D = 125\text{ mA}$		0.48		S
Source-Drain Diode Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = 10\text{ mA}$		0.6	1.0	V

### CAPACITANCES

Input Capacitance	$C_{ISS}$	$f = 1.0\text{ MHz}, V_{GS} = 0\text{ V}$ $V_{DS} = 15\text{ V}$		12.5		pF
Output Capacitance	$C_{OSS}$			3.6		
Reverse Transfer Capacitance	$C_{RSS}$			2.6		

### SWITCHING CHARACTERISTICS, $V_{GS} = 4.5\text{ V}$ (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 4.5\text{ V}, V_{DD} = 10\text{ V}, I_D = 200\text{ mA},$ $R_G = 2.0\ \Omega$		16.5		ns
Rise Time	$t_r$			25.5		
Turn-Off Delay Time	$t_{d(OFF)}$			142		
Fall Time	$t_f$			80		

4. Switching characteristics are independent of operating junction temperatures.

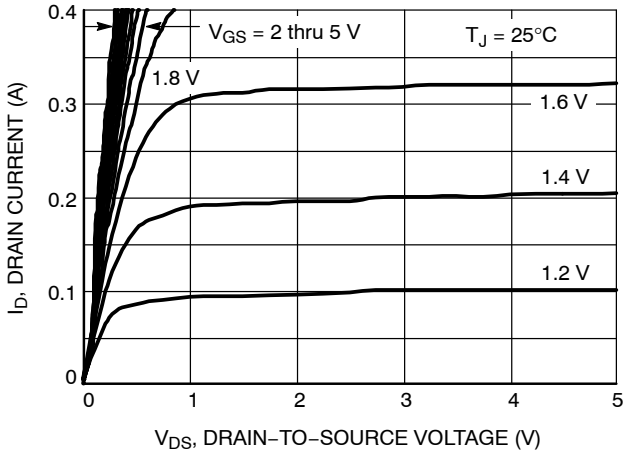
### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTUD3170Nzt5G	SOT-963 (Pb-Free)	8000 / Tape & Reel

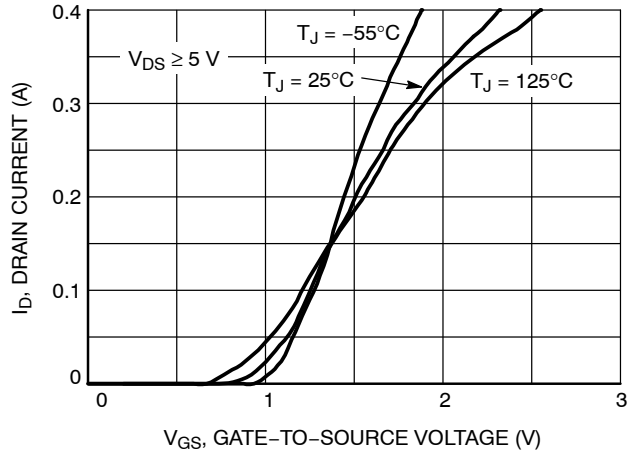
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**NTUD3170NZ**

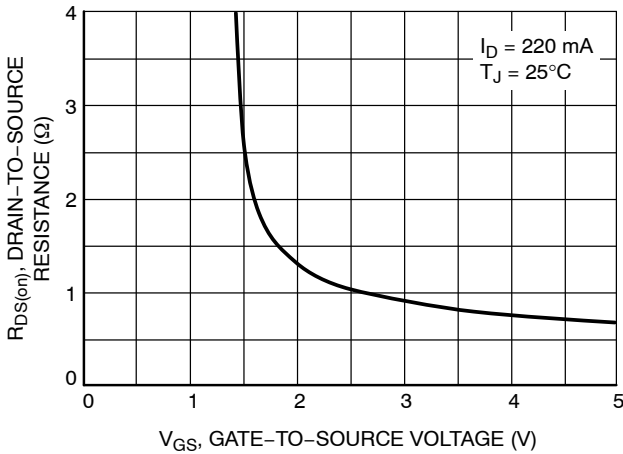
**TYPICAL CHARACTERISTICS**



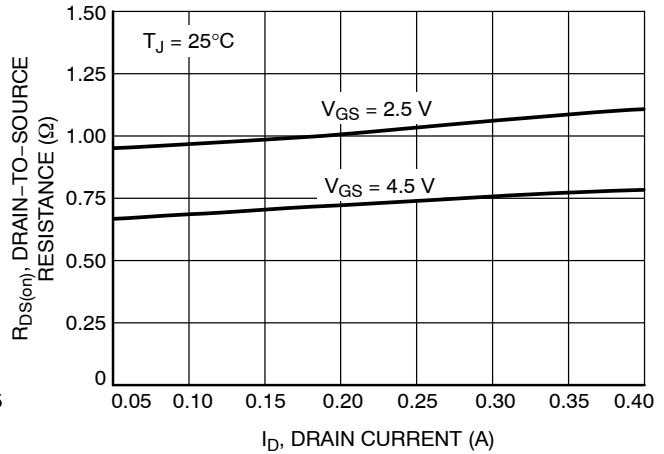
**Figure 1. On-Region Characteristics**



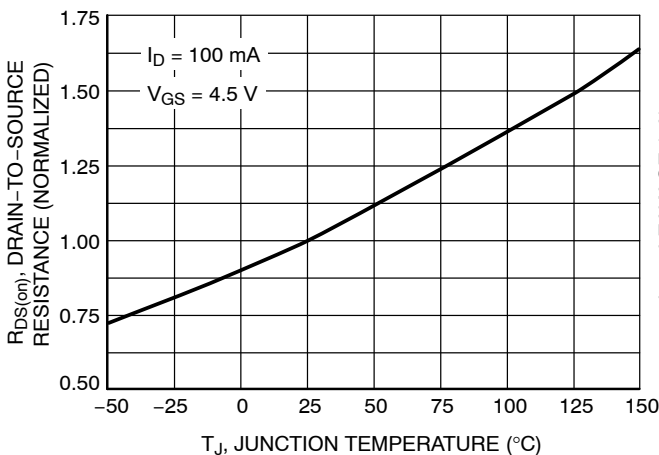
**Figure 2. Transfer Characteristics**



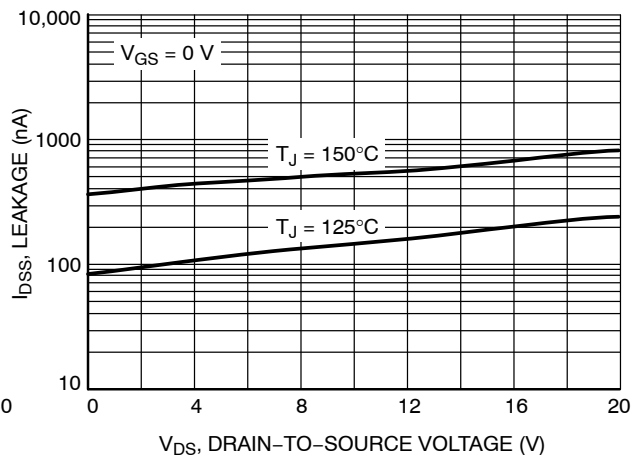
**Figure 3. On-Resistance vs. Gate Voltage**



**Figure 4. On-Resistance vs. Drain Current and Gate Voltage**



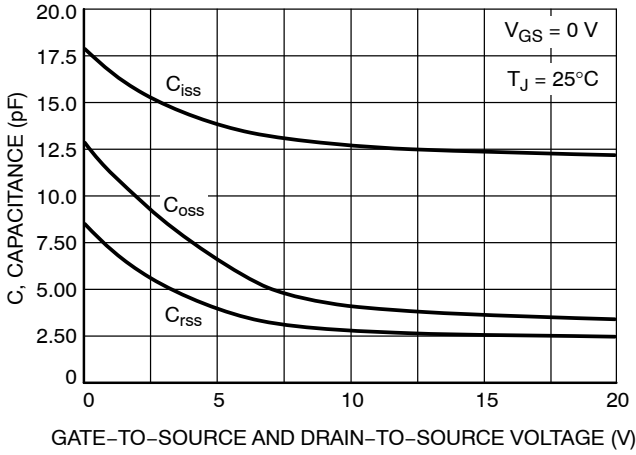
**Figure 5. On-Resistance Variation with Temperature**



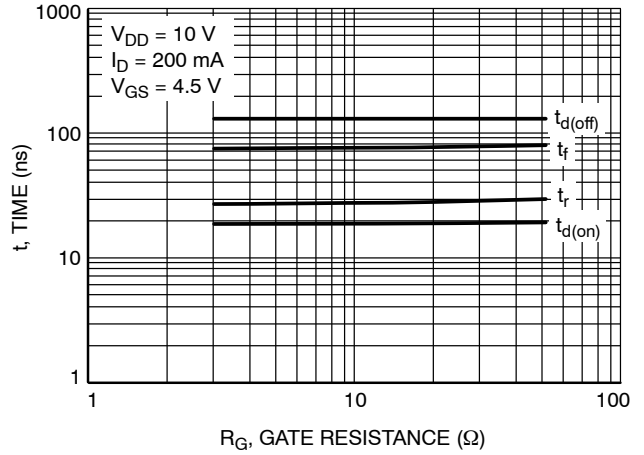
**Figure 6. Drain-to-Source Leakage Current vs. Voltage**

**NTUD3170NZ**

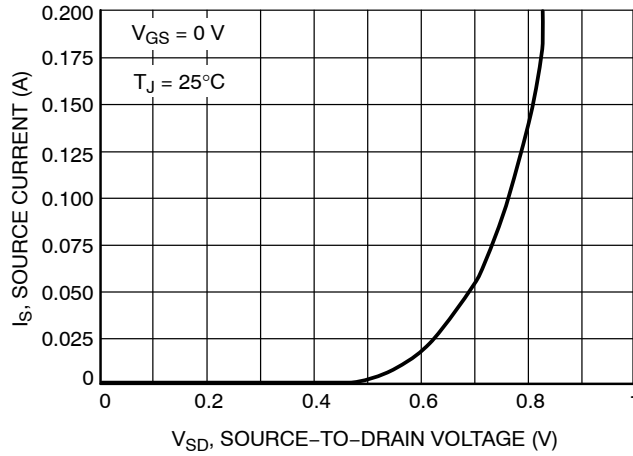
**TYPICAL CHARACTERISTICS**



**Figure 7. Capacitance Variation**



**Figure 8. Resistive Switching Time Variation vs. Gate Resistance**

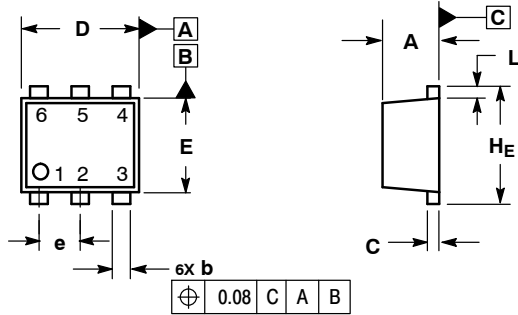


**Figure 9. Diode Forward Voltage vs. Current**

## NTUD3170NZ

### PACKAGE DIMENSIONS

SOT-963  
 CASE 527AD-01  
 ISSUE D

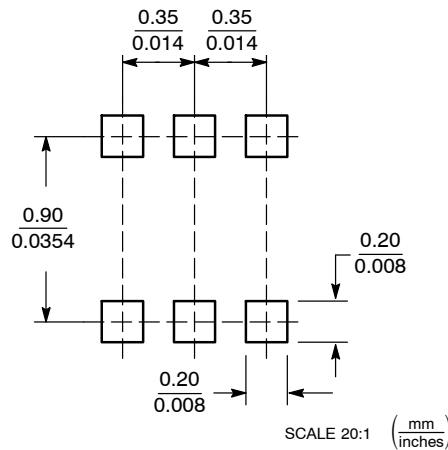


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.34	0.37	0.40			
b	0.10	0.15	0.20	0.004	0.006	0.008
C	0.07	0.12	0.17	0.003	0.005	0.007
D	0.95	1.00	1.05	0.037	0.039	0.041
E	0.75	0.80	0.85	0.03	0.032	0.034
e	0.35 BSC			0.014 BSC		
L	0.05	0.10	0.15	0.002	0.004	0.006
HE	0.95	1.00	1.05	0.037	0.039	0.041

### SOLDERING FOOTPRINT\*



SCALE 20:1 (mm/inches)

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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